Title (en)

RESIN COMPOSITION FOR SEALING

Title (de)

HARZZUSAMMENSETZUNG ZUR VERSIEGELUNG

Title (fr)

COMPOSITION DE RÉSINE POUR FAIRE ÉTANCHÉITÉ

Publication

EP 2805997 A4 20150909 (EN)

Application

EP 13738790 A 20130115

Priority

- JP 2012006463 A 20120116
- JP 2013050509 W 20130115

Abstract (en)

[origin: EP2805997A1] Provided is a sealing resin composition simultaneously having good transparency, resistance to moisture permeability, and adhesiveness resistant to heat and humidity, and a sealing resin composition sheet obtained therefrom. Using a resin composition containing (A) a styrene-isobutylene modified resin and (B) a tackifier resin as a sealing resin composition, a resin composition layer composed of the resin composition is formed on a support to give a sealing resin composition sheet.

IPC 8 full level

C08L 53/00 (2006.01); **C08L 23/26** (2006.01); **C08L 25/08** (2006.01); **C08L 45/00** (2006.01); **C08L 57/02** (2006.01); **C08L 63/00** (2006.01); **C09K 3/10** (2006.01); **H01L 51/50** (2006.01); **H05B 33/04** (2006.01)

CPC (source: EP US)

C08L 23/22 (2013.01 - EP US); **C08L 53/005** (2013.01 - EP US); **C08L 63/00** (2013.01 - EP US); **C09K 3/1006** (2013.01 - EP US); **H10K 50/841** (2023.02 - EP US); **H10K 71/00** (2023.02 - US); C09K 2200/0617 (2013.01 - EP US); C09K 2200/0632 (2013.01 - EP US); H10K 50/844 (2023.02 - EP US)

C-Set (source: EP US)

1. **C08L 23/22** + **C08L 101/00**
2. **C08L 53/005** + **C08L 91/00**
3. **C08L 53/005** + **C08L 63/00**
4. **C08L 63/00** + **C08L 53/005** + **C08L 57/02**

Citation (search report)

- [X] EP 1674432 A1 20060628 - KANEKA CORP [JP]
- [X] WO 9211295 A1 19920709 - EXXON CHEMICAL PATENTS INC [US]
- [X] JP 2000096019 A 20000404 - KANEGAFUCHI CHEMICAL IND
- See also references of WO 2013108731A1

Cited by

CN114450159A

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

EP 2805997 A1 20141126; **EP 2805997 A4 20150909**; **EP 2805997 B1 20230308**; CN 104039888 A 20140910; JP 5983630 B2 20160906; JP WO2013108731 A1 20150511; KR 101969288 B1 20190417; KR 20140121843 A 20141016; TW 201343761 A 20131101; TW I576385 B 20170401; US 2014323669 A1 20141030; US 9676978 B2 20170613; WO 2013108731 A1 20130725

DOCDB simple family (application)

EP 13738790 A 20130115; CN 201380005508 A 20130115; JP 2013050509 W 20130115; JP 2013554284 A 20130115; KR 20147022658 A 20130115; TW 102101490 A 20130115; US 201414331421 A 20140715